MOS FIELD EFFECT TRANSISTOR NP100P06PDG

SWITCHING **P-CHANNEL POWER MOSFET**

DESCRIPTION

NEC

The NP100P06PDG is P-channel MOS Field Effect Transistor designed for high current switching applications.

ORDERING INFORMATION <R>

PART NUMBER	LEAD PLATING	PACKING	PACKAGE	
NP100P06PDG-E1-AY Note		Tape 800 p/reel		
NP100P06PDG-E2-AY Note	100P06PDG-E2-AY Note Pure Sn (Tin)		TO-263 (MP-25ZP)	

Note Pb-free (This product does not contain Pb in external electrode.)

FEATURES

• Super low on-state resistance

 $R_{DS(on)1} = 6.0 \text{ m}\Omega \text{ MAX.}$ (Vgs = -10 V, ID = -50 A)

 $R_{DS(on)2} = 7.8 \text{ m}\Omega \text{ MAX.}$ (Vgs = -4.5 V, ID = -50 A)

• High current rating: ID(DC) = ∓100 A

ABSOLUTE MAXIMUM RATINGS (TA = 25°C)

Drain to Source Voltage (V _{GS} = 0 V)	VDSS	-60	V
Gate to Source Voltage (VDS = 0 V)	Vgss	∓20	V
Drain Current (DC) (Tc = 25°C)	D(DC)	∓100	А
Drain Current (pulse) ^{Note1}	D(pulse)	∓300	А
Total Power Dissipation (Tc = 25°C)	PT1	200	W
Total Power Dissipation (T _A = 25°C)	Pt2	1.8	W
Channel Temperature	Tch	175	°C
Storage Temperature	Tstg	-55 to +175	°C
Single Avalanche Current Note2	las	64	А
Single Avalanche Energy Note2	Eas	420	mJ

Notes 1. PW \leq 10 μ s, Duty Cycle \leq 1%

2. Starting T_{ch} = 25°C, V_{DD} = -30 V, R_G = 25 Ω , V_{GS} = $-20 \rightarrow 0$ V

THERMAL RESISTANCE

Channel to Case Thermal Resistance	Rth(ch-C)	0.75	°C/W
Channel to Ambient Thermal Resistance	Rth(ch-A)	83.3	°C/W

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(TO-263)

The mark <R> shows major revised points.

The revised points can be easily searched by copying an "<R>" in the PDF file and specifying it in the "Find what:" field.

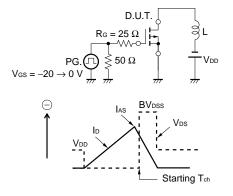
CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Zero Gate Voltage Drain Current	IDSS	V _{DS} = -60 V, V _{GS} = 0 V			-10	μA
Gate Leakage Current	Igss	V _{GS} = ∓20 V, V _{DS} = 0 V			∓100	nA
Gate to Source Threshold Voltage	V _{GS(th)}	V _{DS} = −10 V, I _D = −1 mA	-1.0	-1.6	-2.5	V
Forward Transfer Admittance Note	y _{fs}	V _{DS} = -10 V, I _D = -50 A	43	86		S
Drain to Source On-state Resistance Note	RDS(on)1	V _{GS} = -10 V, I _D = -50 A		4.4	6.0	mΩ
	RDS(on)2	V _{GS} = -4.5 V, I _D = -50 A		5.0	7.8	mΩ
Input Capacitance	Ciss	V _{DS} = -10 V,		15000		pF
Output Capacitance	Coss	V _{GS} = 0 V,		1810		pF
Reverse Transfer Capacitance	Crss	f = 1 MHz		840		pF
Turn-on Delay Time	td(on)	V_{DD} = -30 V, I _D = -45 A,		28		ns
Rise Time	tr	V _{GS} = -10 V,		35		ns
Turn-off Delay Time	td(off)	R _G = 0 Ω		275		ns
Fall Time	tr			100		ns
Total Gate Charge	QG	V _{DD} = -48 V,		300		nC
Gate to Source Charge	QGS	V _{GS} = -10 V,		35		nC
Gate to Drain Charge	Qgd	I⊳ = −100 A		85		nC
Body Diode Forward Voltage Note	V _{F(S-D)}	I⊧ = −100 A, V _{GS} = 0 V		0.92	1.5	V
Reverse Recovery Time	trr	I⊧ = −100 A, V₀s = 0 V,		67		ns
Reverse Recovery Charge	Qrr	di/dt = −100 A/ <i>µ</i> s		135		nC

ELECTRICAL CHARACTERISTICS (TA = 25°C)

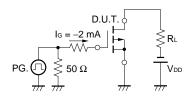
Note Pulsed test PW \leq 350 μ s, Duty Cycle \leq 2%

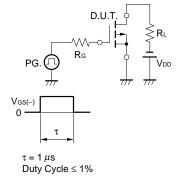
TEST CIRCUIT 1 AVALANCHE CAPABILITY

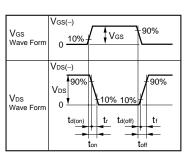
TEST CIRCUIT 2 SWITCHING TIME



TEST CIRCUIT 3 GATE CHARGE







100 125 150 175 200

Tc - Case Temperature - °C

TOTAL POWER DISSIPATION vs.

CASE TEMPERATURE

240

200

160

120

80

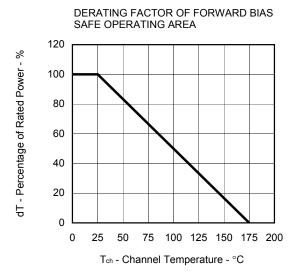
40

0

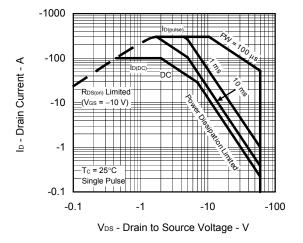
0 25 50 75

 P_{T} - Total Power Dissipation - W

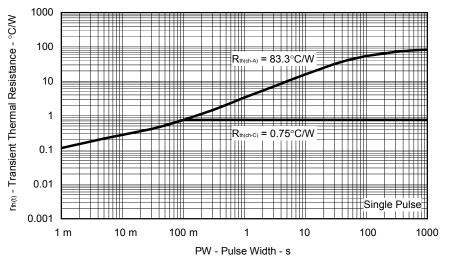
TYPICAL CHARACTERISTICS (T_A = 25°C)





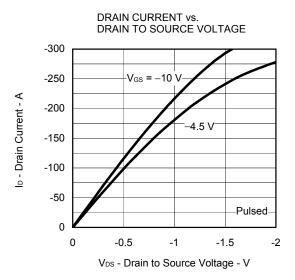


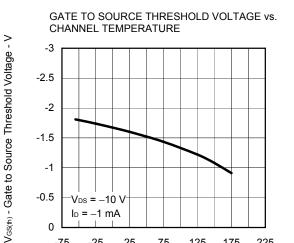




Data Sheet D18693EJ3V0DS







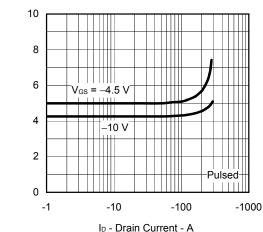
75 Tch - Channel Temperature - °C

125

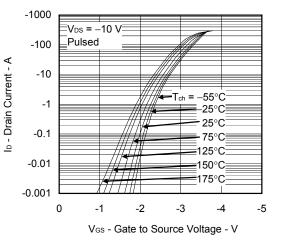
175

225

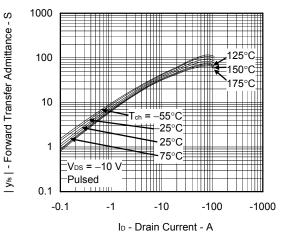
DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT



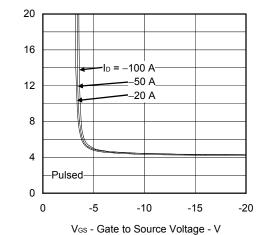




FORWARD TRANSFER ADMITTANCE vs. DRAIN CURRENT



DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE



 $R_{DS(on)}$ - Drain to Source On-state Resistance - $m\Omega$

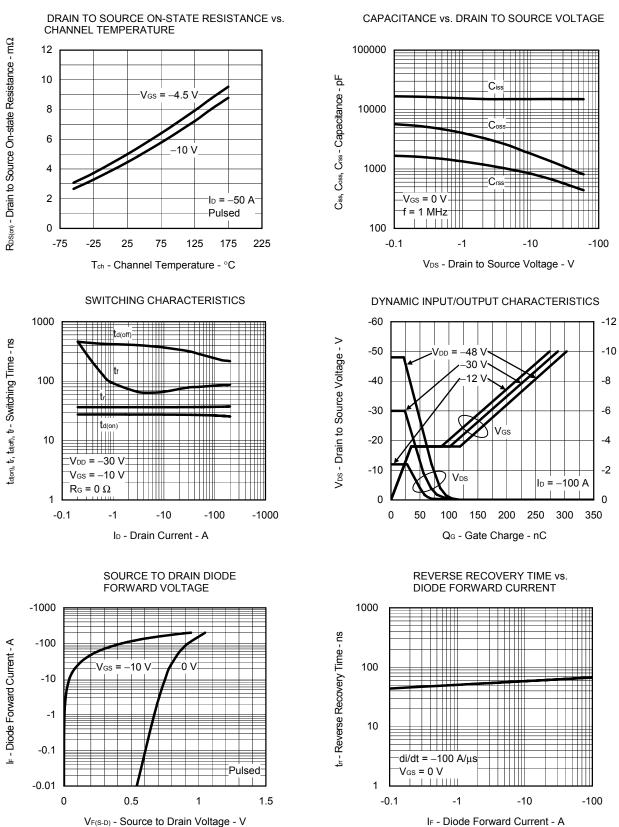
0

-75

-25

25

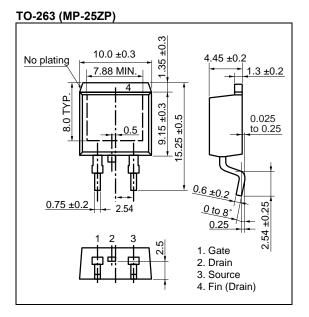
 $R_{DS(m)}$ - Drain to Source On-state Resistance - $m\Omega$



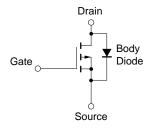
VF(S-D) - Source to Drain Voltage - V

V_{GS} - Gate to Source Voltage - V

PACKAGE DRAWING (Unit: mm)



EQUIVALENT CIRCUIT



Remark Strong electric field, when exposed to this device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop generation of static electricity as much as possible, and quickly dissipate it once, when it has occurred.

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